



Product Features

- 30 ~ 2650MHz
- Small Size
- High Gain
- High Linearity
- Low Cost

Applications

- Low Noise Amplifier for CATV, Satellite
- Cable Modem
- FTTH (G-PON, GE-PON)
- Optical Node



Package Type : SOT-89

Description

AE305 is designed as low cost drive amplifiers for many applications including FTTH, CATV System. This MMIC is based on Gallium Arsenide Enhancement Mode pHEMT which shows low current draw and very low noise. The data in this spec sheet is valid only for 75 ohm application. 50 ohm data is in a separate spec sheet.

Electrical Specifications

PARAMETER	UNIT	MIN	TYP	MAX	CONDITION	
Frequency	MHz	30	-	2650	-	
Gain	dB	-	14.5 13.5	-	30 ~ 1000MHz 30 ~ 2650MHz	
Gain Flatness	dB	-	1	-	30 ~ 1400MHz	
Input Return Loss	dB	-	-15	-10	-	
Output Return Loss	dB	-	-10	-7	-	
Output IP3	dBm	35	38	-	@ 500MHz/5dBm 2tone	
1dB Compression Point	dBm	20	22	-	@ 500MHz	
Noise Figure	dB	-	2.3	3	30 ~ 1000MHz	
CSO	30 ~ 870MHz	dBc	-	-60	-55	135 channel, +30dBmV/ch
CTB		dBc	-	-68	-63	135 channel, +30dBmV/ch
XMOD		dBc	-	-68	-63	135 channel, +30dBmV/ch
DC Current	mA	-	110	-	Vdd = 5.0V	

Note

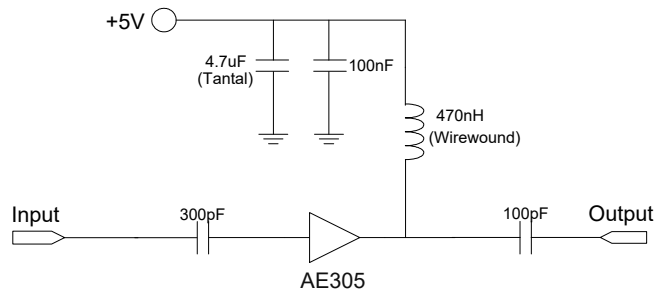
1. Test conditions unless otherwise noted. Test Freq = 500MHz, T=25°C, Vdd=5V, 75Ω system
2. OIP3 measured with 2 tones at an output power of +5dBm/tone separated by 1MHz, Test Freq = 500MHz

Absolute Maximum Ratings

PARAMETER	UNIT	MIN	TYP	MAX
Device Voltage	VDC	-	5	12
Operating Temperature	°C	-40	-	85
Storage Temperature	°C	-40	-	150
ESD Human Body Model	-	-	Class 1A	-
Moisture sensitivity Level	-	-	MSL1	-
Junction temperature	-	-	-	180
Thermal Resistance (Rth)	-	-	70	-

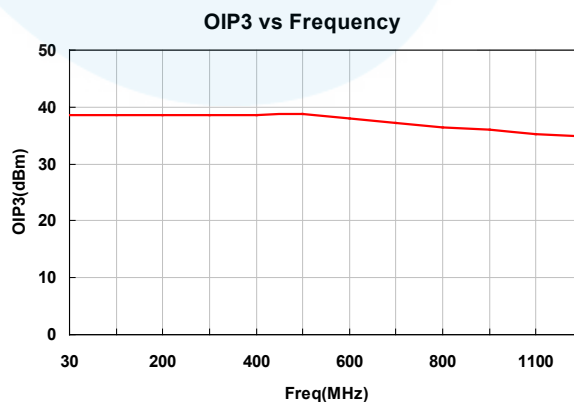
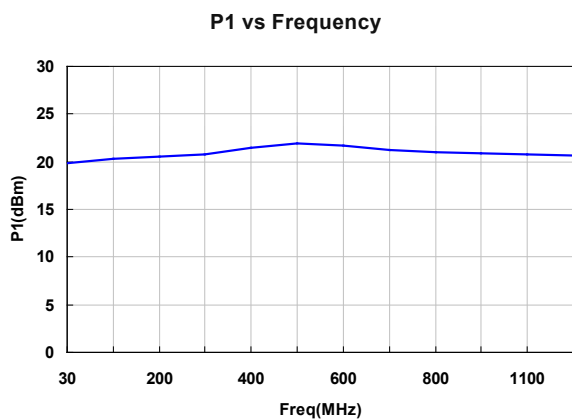
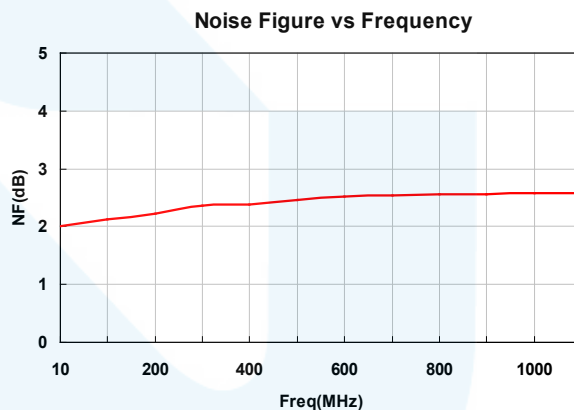
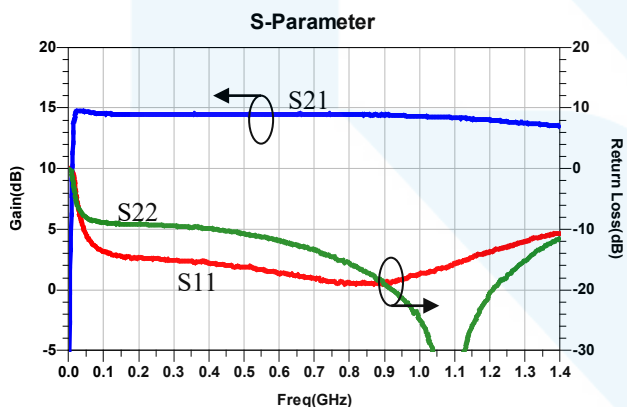
Application Circuit : 30 ~ 1000MHz, 75ohm System

PARAMETER	UNIT	TYPICAL		
Frequency	MHz	50	500	1000
Gain(S21)	dB	14.5		
IRL(S11)	dB	-11	-16	-17
ORL(S22)	dB	-8	-10	-23
Output IP3	dBm	38.5	38.5	35
P1dB	dBm	20	21.5	21
Noise Figure	dB	2	2.4	2.6
CSO(1)	dBc	-60		
CTB(1)	dBc	-68		
XMOD(1)	dBc	-68		
Current	mA	110		



(1) 135channels, +30dBmV/ch

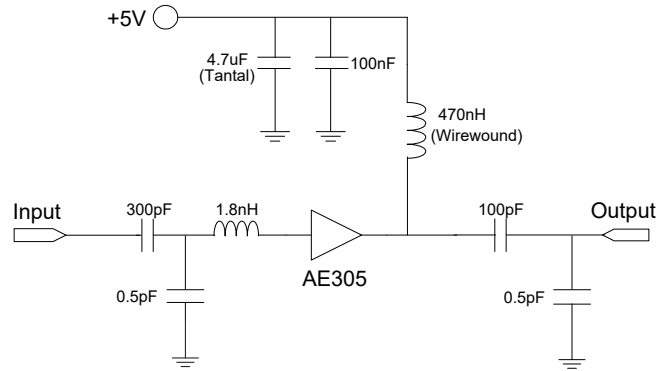
Typical Performance @ VDD=5V, IDS=110mA, T=25°C, 75ohm System



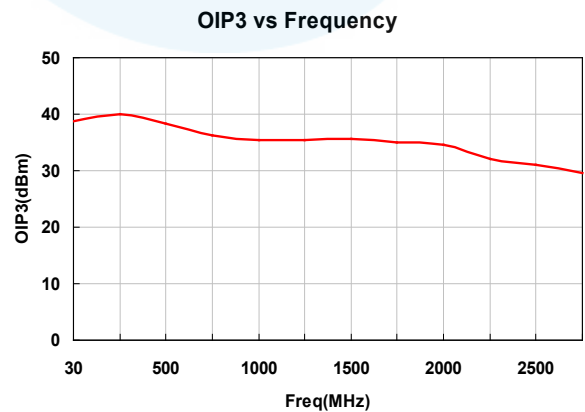
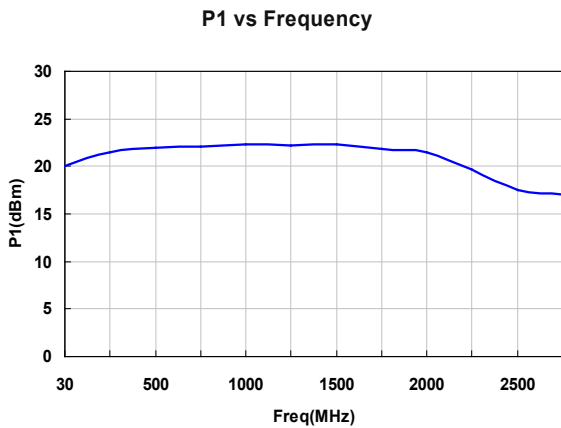
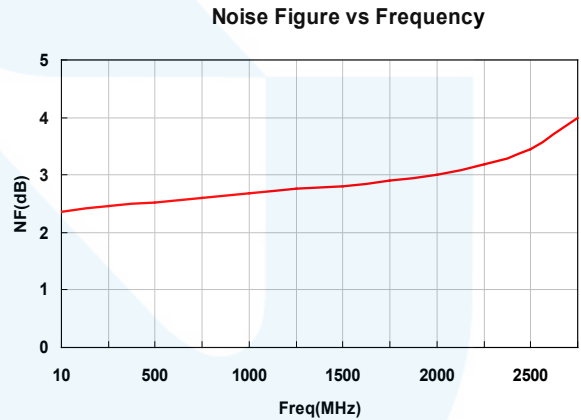
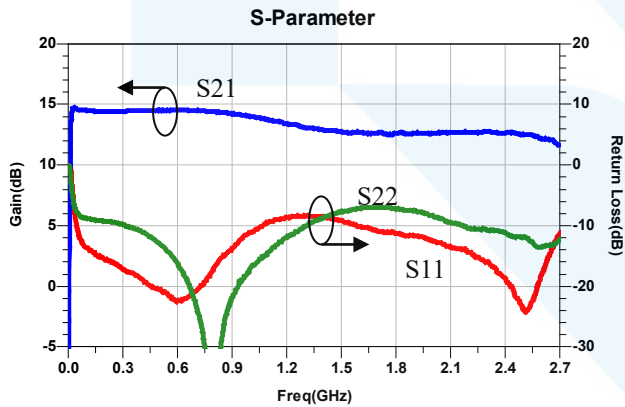
Application Circuit @ 30 ~ 2650MHz, 75ohm System

PARAMETER	UNIT	TYPICAL			
		50	1000	2000	2650
Frequency	MHz	50	1000	2000	2650
Gain(S21)	dB	13.5			
IRL(S11)	dB	-11	-11	-12.5	-14
ORL(S22)	dB	-8	-16	-8	-13
Output IP3	dBm	38.5	35.5	34.5	29.5
P1dB	dBm	20	22	21.5	17
Noise Figure	dB	2.5	2.7	3	4
CSO(1)	dBc	-60			
CTB(1)	dBc	-68			
XMOD(1)	dBc	-68			
Current	mA	110			

(1) 135channels, +30dBmV/ch



Typical Performance @ VDD=5V, IDS=110mA, T=25°C, 75ohm System

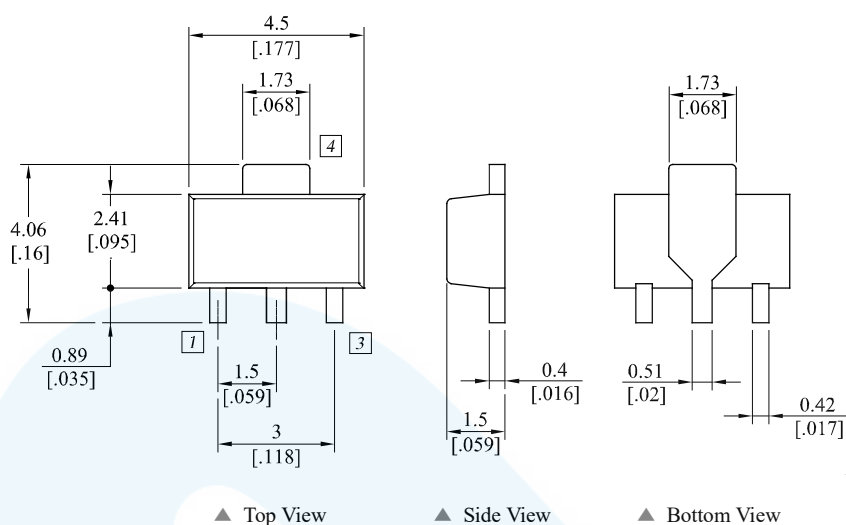


Multi-Tone Test : 135CH_FLAT@Output Power +30dBmV/Ch

Level: +30dBmV Tilt: 135CH_FLAT										
FRQ	XMD (NCTA)	CTB RAW	CTB COR	N-FLR	CSU RAW	CSU COR	CSU FRQ	CSL RAW	CSL COR	CSL FRQ
55.25	71.3	76.1	80.4	77.4	76.3	80.6	55.99	59.7	59.7	53.99
77.25	74.2	76.7	81	77.4	60	60	77.99	77.2	81.5	75.98
109.25	74.7	75.9	80.2	77.5	74.9	79.2	109.99	60.2	60.2	107.99
211.25	74.4	75.8	80.1	77.7	74.4	77	212.49	61.6	61.7	209.99
331.25	74.4	73.2	76.2	76.1	71.2	72.9	332.49	62.1	62.3	329.98
445.25	73.6	72.7	74.6	77.2	70.8	72.1	446.49	63.1	63.2	443.99
547.25	71.9	70.9	73.1	74.9	67.5	68.3	548.49	62.4	62.6	545.98
637.25	71.1	69.7	71.1	75.2	66.3	66.9	638.49	64	64.3	635.98
745.25	70.7	69.4	70.8	74.9	65	65.5	746.48	67	67.7	743.99
859.25	68.9	68.9	70.8	73.4	63.9	64.4	860.49	71.5	75.8	858.49
Min	68.9	68.9	70.8	73.4	60	60	55.99	59.7	59.7	53.99
Max	74.7	76.7	81	77.7	76.3	80.6	860.49	77.2	81.5	858.49

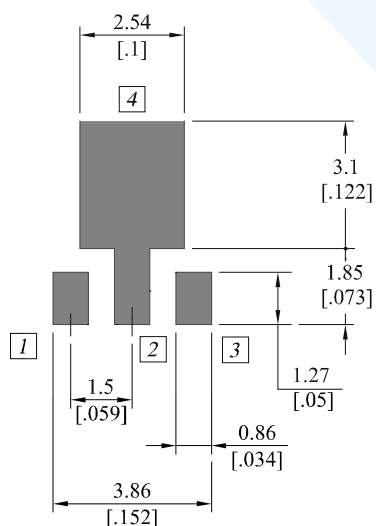
Package Dimensions (Type: SOT-89)

* Unit: mm[inch] | Tolerance ± 0.2 [.008]

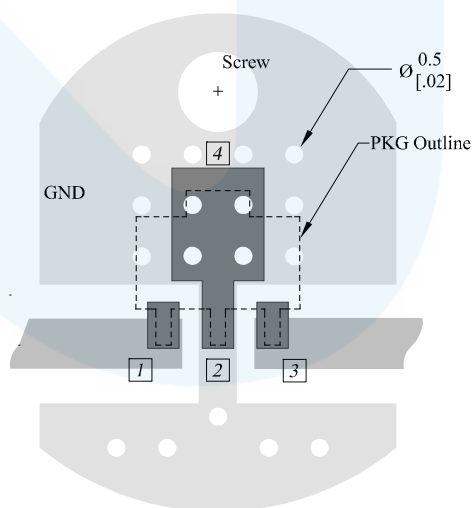


Pin Description			
Pin No	Function	Pin No	Function
1	Input	4	GND
2	GND	-	-
3	Output / Bias	-	-

Recommended Pattern



Recommended Mounting Configuration



* Mounting Configuration Notes

1. Ground / thermal via holes are critical for the proper performance of this device.
2. Add as much copper as possible to inner and outer layers near the part to ensure optimal thermal performance.
3. Mounting screws can be added near the part to fasten the board to a heatsink. Ensure that the ground / thermal via hole region contacts the heatsink.
4. Do not put solder mask on the backside of the PCB in the region where the board contacts the heatsink.
5. RF trace width depends upon the PCB material and construction.
6. Use 1 oz. Copper minimum.

Revision History

Part Number	Release Date	Version	Modification	Data Sheet Status
AE305	2014.04.22	1.2	Absolute Maximum Ratings (Delete Tj Typ)	-
AE305	2012.10.15	1.1	New datasheet format	-



Certification

This product is manufactured by a company that is certified for the AS9100D quality management system.

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